

AGENDA, EUROPEAN IBIS SUMMIT MEETING

Wednesday, May 13, 2015

Seminaris Campus Hotel Berlin/ Dahlem Cube
Takustraße 39, 14195
Berlin, Germany

Room: Cambridge (Check at Entrance)

13:00 SIGN IN

13:15 WELCOME AND INTRODUCTIONS

Randy WOLFF, Micron Technology, IBIS Secretary, USA

13:30 Physics and Modeling of Vias in Printed Circuit Boards

Jan PREIBISCH and Christian SCHUSTER,
Technische Universität Hamburg-Harburg, Germany
[Presented by Jan PREIBISCH]

14:30 Chair's Status Report

Michael MIRMAK, Intel Corporation USA
[Presented by Randy WOLFF, Micron Technology, USA]

15:00 IBIS Model Formulation and Extraction for SPI Evaluation

Wael DGHAIS, Kevin F.G. PINTO, and Jonathan RODRIGUEZ;
University of Aveiro, Institute of Telecommunications,
Portugal
[Presented by Wael DGHAIS]

15:30 BREAK (15 Minutes)

15:45 [Define Package Model] Proposed Extension

Randy WOLFF*, Radek BIERNACKI**, and Bob ROSS***,
*Micron Technology, **Keysight Technology, and
***Teraspeed Labs, USA
[Presented by Randy WOLFF]

16:15 Interconnect Task Group Update - Package Modeling

Randy WOLFF, Micron Technology, USA

16:45 Time Response Utility

Bob ROSS, Teraspeed Labs, USA
[Presented by Anders EKHOLM, Ericsson, Sweden]

17:15 DISCUSSION AND CLOSING REMARKS

Randy WOLFF, Micron Technology, USA

18:00 END OF MEETING